Product data sheet

1. General description

Standard reverse recovery power diode in a TO220F package.





2. Features and benefits

- · Low forward voltage drop
- Low leakage current
- · High voltage capability
- · High inrush current capability

3. Applications

- · Input rectifier
- · Bypass diode

4. Quick reference data

Table 1. Quick reference data

| Symbol | ol Parameter Conditions | | , | Values | | | | |
|--|---------------------------------|--|-------------|--------|------|---|--|--|
| Absolute | Absolute maximum rating | | | | | | | |
| V_{RRM} | repetitive peak reverse voltage | | | 800 | | V | | |
| I _{F(AV)} | average forward current | δ = 0.5; square-wave pulse; <u>Fig. 1</u> ; <u>Fig. 2</u> | | 35 | | Α | | |
| I _{FSM} non-repetitive peak forward current | | t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 3 | 400 | | А | | | |
| | | t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse | 435 | | А | | | |
| Symbol | Parameter | Conditions | Min Typ Max | | Unit | | | |
| Static ch | aracteristics | | | | | | | |
| V _F | forward voltage | I _F = 20 A; T _j = 25 °C; <u>Fig. 5</u> | - | 1.05 | 1.25 | V | | |
| | | I _F = 20 A; T _j = 150 °C; <u>Fig. 5</u> | - | 1.00 | 1.20 | V | | |
| | | I _F = 35 A; T _j = 25 °C; <u>Fig. 5</u> | - | 1.18 | 1.40 | V | | |
| | | I _F = 35 A; T _j = 150 °C; <u>Fig. 5</u> | - | 1.15 | 1.35 | V | | |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------------------|--------------------|----------------|
| 1 | K | cathode | mb | K — A |
| 2 | А | anode | | 001aaa020 |
| mb | n.c. | mounting base; isolated | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package Orderable part num | | ble part number Packing Sma | | Package | Package | | |
|-------------|----------------------------|------------|-----------------------------|----------|---------|---------------|--|--|
| | name | | method | quantity | version | issue date | | |
| WND35P08X | TO220F-2L | WND35P08XQ | Tube | 50 | SOD113A | 10-April-2014 | | |

7. Marking

Table 4. Marking codes

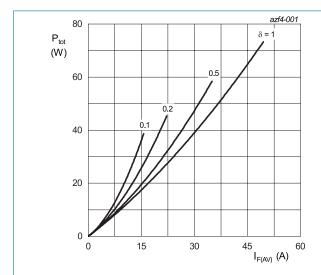
| Type number | Marking codes |
|-------------|---------------|
| WND35P08X | WND35P08X |

8. Limiting values

Table 5. Limiting values

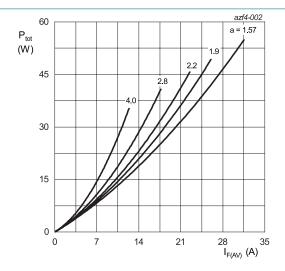
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Values | Unit |
|--------------------|-------------------------------------|---|------------|------------------|
| V_{RRM} | repetitive peak reverse voltage | | 800 | V |
| V_{RWM} | crest working reverse voltage | | 800 | V |
| V_R | reverse voltage | DC | 800 | V |
| I _{F(AV)} | average forward current | δ = 0.5 ; square-wave pulse; Fig. 1; Fig. 2 | 35 | А |
| I _{FSM} | non-repetitive peak forward current | t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 3 | 400 | А |
| | | t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse | 435 | Α |
| l ² t | I ² t for fusing | sine-wave pulse; $T_{j(init)} = 25 ^{\circ}\text{C}$; $t_p = 10 \text{ms}$ | 800 | A ² s |
| T _{stg} | storage temperature | | -40 to 150 | °C |
| T _j | junction temperature | | -40 to 150 | °C |



$$\begin{split} I_{F(AV)} &= I_{F(RMS)} \times \sqrt{\delta} \\ V_o &= 1.025 \text{ V}; \text{ R}_s = 0.0092 \text{ } \Omega \end{split}$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor = $I_{F(RMS)}$ / $I_{F(AV)}$ V_o = 1.025 V; R_s = 0.0092 Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

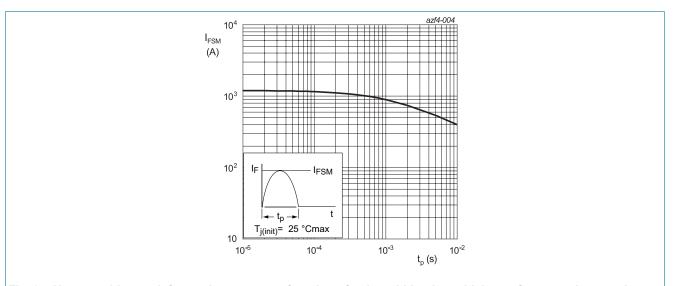
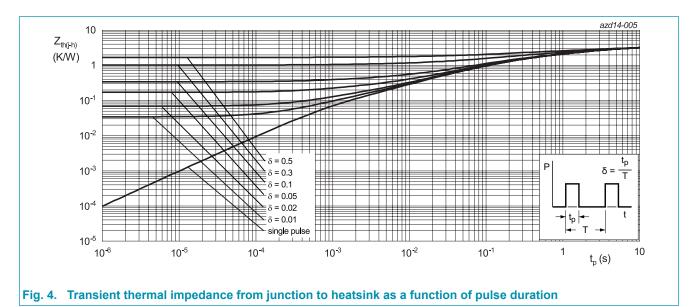


Fig. 3. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|----------------------|--|-------------|-----|-----|-----|------|
| $R_{th(j-h)}$ | thermal resistance from junction to heatsink | Fig. 4 | - | - | 3.2 | K/W |
| $R_{\text{th(j-a)}}$ | thermal resistance from junction to ambient free air | in free air | - | 60 | - | K/W |



10. Isolation characteristics

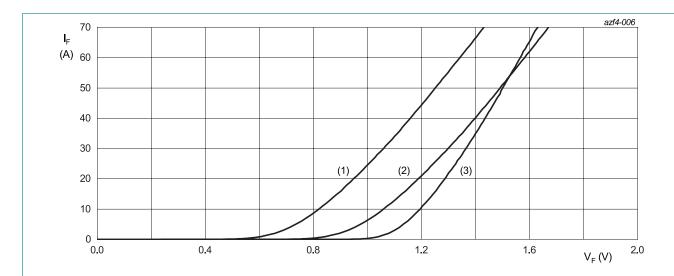
Table 7. Isolation characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|------------------------|-----------------------|--|-----|-----|------|------|
| V _{isol(RMS)} | RMS isolation voltage | 50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free | - | - | 2500 | V |
| C _{isol} | isolation capacitance | from cathode to external heatsink | - | 10 | - | PF |

11. Characteristics

Table 8. Characteristics

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|----------------|---|---|--|-----|------|------|------|
| Static cha | Static characteristics | | | | | | |
| V_{F} | forward current | I _F = 20 A; T _j = 25 °C; <u>Fig. 5</u> | | - | 1.05 | 1.25 | V |
| | | I _F = 20 A; T _j = 150 °C; <u>Fig. 5</u> | | - | 1.00 | 1.20 | V |
| | | I _F = 35 A; T _j = 25 °C; <u>Fig. 5</u> | | - | 1.18 | 1.40 | V |
| | | I _F = 35 A; T _j = 150 °C; <u>Fig. 5</u> | | - | 1.15 | 1.35 | V |
| I _R | reverse current $V_R = 1600 \text{ V}; T_j = 25 \text{ °C}$ | | | - | - | 50 | μA |
| | | V _R = 1600 V; T _j = 150 °C | | - | - | 1 | mA |

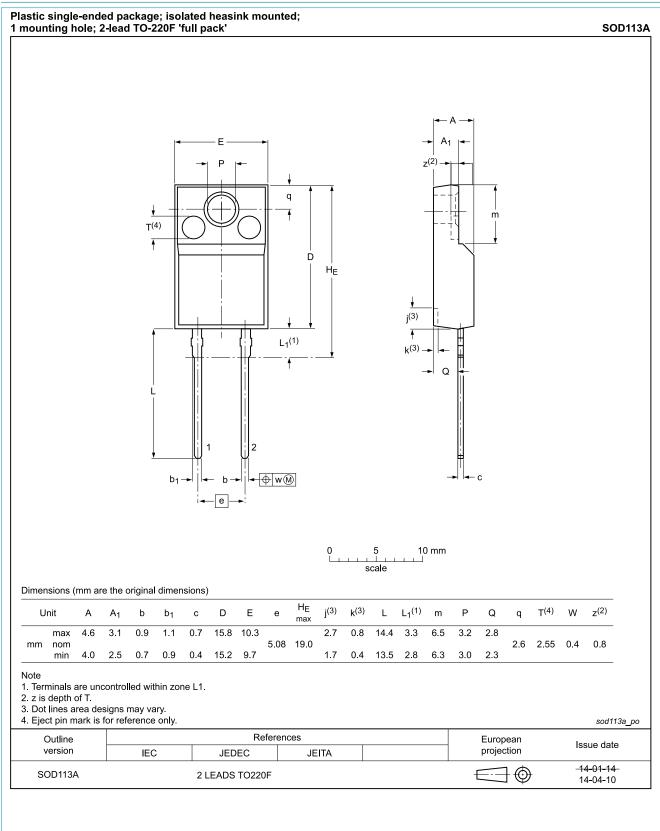


 V_o = 1.025 V; R_s = 0.0092 Ω

(1) $T_i = 150 \,^{\circ}\text{C}$; typical values (2) $T_j = 150 \,^{\circ}\text{C}$; maximum values (3) $T_j = 25 \,^{\circ}\text{C}$; maximum values

Fig. 5. Forward current as a function of forward voltage

12. Package outline



13. Legal information

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| Document status [1][2] | Product status [3] | Definition |
|--------------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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